

# **LX7730 Datasheet List of Changes**

## **Rev0.98 - Rev0.97**

### 1. Page 9, EC Table.

Is:

IVCC	VCC Normal Current		38	70	85	mA
IVEE	VEE Current	Using external VEE source. Positive current out of pin.	-2	-4.7	-7.0	mA

Was:

IVCC	VCC Normal Current		55	70	85	mA
IVEE	VEE Current	Using external VEE source. Positive current out of pin.	-3.5	-4.7	-6.0	mA

### 2. Page 9, EC Table.

Is:

V <sub>VEE</sub>	VEE UVLO	Voltage falling; 200mV Hysteresis	-8.2	-8.0	-7.5	V
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Was:

V <sub>VEE</sub>	VEE UVLO	Voltage falling; 200mV Hysteresis	-8.2	-8.0	-7.8	V
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### 3. Page 9, EC Table

Is:

V <sub>VEE</sub>	VEE voltage	VCC -  V <sub>VEE</sub>	1.5	2.6	3	V
V <sub>+5V_NOM</sub>	+5V voltage		4.75	5.00	5.25	V

Was:

V <sub>VEE</sub>	VEE voltage	VCC -  V <sub>VEE</sub>	2.0	2.6	2.9	V
V <sub>+5V_NOM</sub>	+5V voltage		4.8	5.00	5.20	V

#### 4. Page 9, EC Table

Is:

V <sub>CH#</sub>	Voltage Clamp (power applied)	Clamp Current = 1mA (into pin) <sup>(1)</sup>	VCC	16	17	V
		Clamp Current = 1mA (out of pin)	-23	-20	-16	
V <sub>CH#</sub>	Voltage Clamp (VCC=VEE=0)	Clamp Current = 1mA (into pin)	16	20	23	V
		Clamp Current = 1mA (out of pin)	-23	-20	-16	

Was:

V <sub>CH#</sub>	Voltage Clamp (power applied)	Clamp Current = 1mA (into pin) <sup>(1)</sup>	15	16	17	V
		Clamp Current = 1mA (out of pin)	-23	-20	-17	
V <sub>CH#</sub>	Voltage Clamp (VCC=VEE=0)	Clamp Current = 1mA (into pin)	17	20	23	V
		Clamp Current = 1mA (out of pin)	-23	-20	-17	

#### 5. Delete EC spec :

I <sub>CH#</sub>	Settling Time	To within 5% tolerance			10	μs
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6. Page 1 & 8, the LX7730 offers 1 kV ESD pin protection on FPGA interface pins and power pins, 500V ESD protection to all CH#, BLI# and the other pins.

It was “1 kV ESD pin protection on all CH# pins and 2kV on the other pins.”

7. Page 1, 3% Precision Adjustable Current Source. Update it to match the EC table spec, it is not a spec change.

It was “2% Precision Adjustable Current Source”

8. Page 4 & 9, add 0.1% resistor tolerance to ADC\_BIAS\_IN and ADC\_DAC\_OUT pins description, add 1% resistor tolerance to IREF1 pin description.

9. Page 5, add “Connect it to ground when not used.” to BL-TH pin description.

10. Page 17, delete “but will not change during the process of a data read which starts by reading the upper byte and ends by reading the lower byte” from 12 bit ADC theory of operation description.



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